

EASYLOG

Wireless Temperature Measurement
during the Pressing of Thin Panels



GreCon®

Wireless Temperature Measurement for an Optimum Pressing Process

Optimize your pressing process by measuring the development of the mat temperature in any position within your press.

The EASYLOG is a wireless sensor with which the temperature of the mat is recorded during pressing. Minimum panel thicknesses from 10 mm.

The temperature measurement provides information on the curing of the resin in the mat and enables you to optimize the press program for your individual recipes. Reach a core layer temperature of 100°C as soon as possible!

Immediately detect the effects of optimization measures on the quality of your products. The effects of changes in surface or core layer moisture, glue structure, particle size, raw density and other parameters can be immediately checked. Even the influence by surface spraying, preheating systems, transport speeds and other upstream processes quickly become apparent.

The temperature can also be measured in downstream processes, such as cooling, conditioning, sanding and coating, by using long-life batteries and programmable measuring phases.

Reduce the start-up time of your press by checking the heat transfer to the core layer of your products in any position.

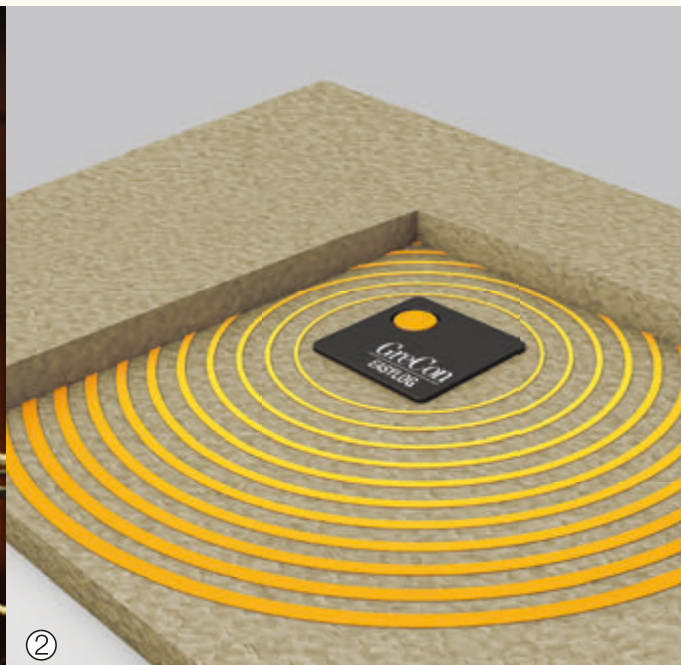
Control the data loggers intuitively using “touch“ with a tablet PC. The tablet PC can be used for both EASYLOG and CONTILOG data loggers.

After leaving the press, the measured data is wirelessly read out with a reader. The data can be transferred to a PC for evaluation using a USB stick.

Measuring Procedure

- Placement of the logger in the core layer of the wood based mat
- Marking of the logger's position on the mat edge
- Continuous measurement of the temperature while running through the hot press
- Synchronise measurement with press inlet and outlet
- Wireless read-out of the data logger

- ① EASYLOG in application ③ Analysis on tablet PC
② Chip within panel ④ Reader with EASYLOG chip within the panel



Your Benefit



- Resin curing information in the panel (reaching of the 100 °C threshold in any position)
- Short start-up times of wood based panel productions
- Optimization of existing press programs
- Recipe adaptations in record time
- Detection of influences of upstream and downstream processes
- Small thickness (2.5 mm)
- Suitable for panels of more than 10 mm thickness
- Temperature measurement during cooling, conditioning, sanding, coating

Technical Specifications

Data Logger

- Dimensions (L x W x H) 64 x 43 x 2,5 mm
- Power supply.....3.0 V
- Interval between two measurementsprogrammable (starting at 0.25 s)

Digital Temperature Sensor

- Measuring range up to +125 °C
- Measuring accuracy..... +/-2 °C
- Panel thickness min. 10 mm
- Radio frequency.....13.56 MHz (RFID)

Reader

- Dimensions (excl. edge protector) approx. 275 x 204 x 27 mm
- Weight approx. 1.1 kg
- Display.....10.1" (1366 x 768)
- Working memory.....2 GB
- Hard disk.....32 GB

References

- Particleboard, OSB, MDF manufacturers
- Insulating material manufacturers (up to 125 °C)
- Original equipment manufacturers (OEM)
- Resin producers
- Research institutes



Why GreCon



- Customer-specific system design
- High innovative capacity: more than 10 % of the employees work in the R & D division
- Worldwide customer service network: more than 80 service technicians on duty worldwide
- Efficient sales network: represented in more than 35 countries
- High expertise: more than 40 years of experience in the measuring technology sector



OUR HEADQUARTERS AT ALFELD - BUILT BY WALTER GROPIUS IN 1911

GreCon

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